SCALE 2.000

NOTES :

I. MATERIAL: HOUSING: HIGH TEMPERATURE THERMOPLASTIC.

UL 94 V-O FLAME RETARDANT.

TERMINAL: COPPER ALLOY.

PLATING SPEC. AS BELOW: Ni 50u" UNDER PLATED.

AU OR GXT OVER CONTACT AREA. (ONE SIDE)

Tin 120u" OVER SOLDERING AREA.

2. PACKING SPEC. GS-14-924.

3. PRODUCT PERFORMANCE PER SPEC. GS-12-285.

4. PART NUMBER SCHEME: (EX. 10056265-222ABTMLF) 10056265-X XX X X X X X LF (LEAD FREE PLATING)



5. Rohs Compatible Product Specifications

a-PLATING:

-"LF" MEANS THE PRODUCT IS LEAD-FREE, 2micro-meter MINIMUM MATTE TIN OVER

1.27micro-meter MINIMUM NICKEL UNDERPLATE.

b-MANUFACTURING PROCESS COMPATIBILITY

-THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C SOLDER BATH TEMPERATURE FOR

5 SECONDS IN A REFLOW SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

| | | | | | www.fciconnect.com | | | | surface tolerar ASME Y14.5 TOLERANCES UNLESS OTHERWISE | | | | projection | - MM | |
|-----|----------|-----|------------|---------------------------|--------------------|-----|------------|---------|--|--------|------|----------|------------|--------------|-------|
| | | | | Dr | KENNY | TAI | 2005-05-12 | ANGULAR | | | 0.X | ±0.50 | size A 4 | Scale | e |
| rev | ecn no | d٢ | date | Eng | KENNY | TAI | 2005-05-12 | ANG | ULAK | LINEAR | 0.XX | ±0.30 | A 4 | 1.00 | 0 l |
| A | T05-0096 | TAI | 2005-05-23 | Chr | KENNY | TAI | 2005-05-12 | 0° ±2° | 1 | 0.XXX | ± | ECN | N08-0069 | | |
| В | T05-0121 | TAI | 2005-06-03 | | _ | | | | | 1 fami | | | | | |
| С | T05-0239 | TAI | 2005-10-19 | Appr PAUL WANG 2005-05-12 | | | | | Product family | | | | Spec ref | | * |
| D | T05-0271 | TAI | 2005-12-08 | | | | | | | | | ٥ | | | Rev. |
| E | T05-0304 | TAI | 2005-12-30 | | | | | | | | | 5 | 100562 | 65 | l G l |
| F | T06-0118 | TAI | 2006-06-15 | | | | | | | | | Μp | | | U |
| G | N08-0069 | R.B | 2008/04/21 | | | | | | 10056265 | | | CUSTOMER | | sheet I of 3 | |

PDM: Rev:G

C.



